

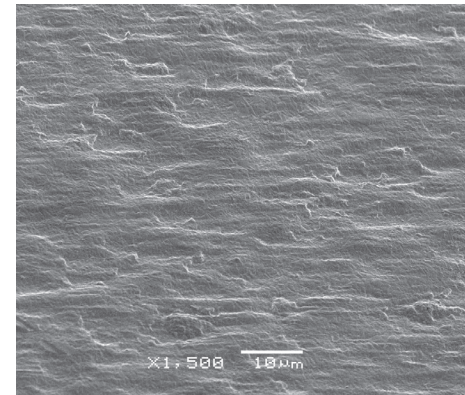
High temperature stability electrodeposited copper foil.

**Applications:**

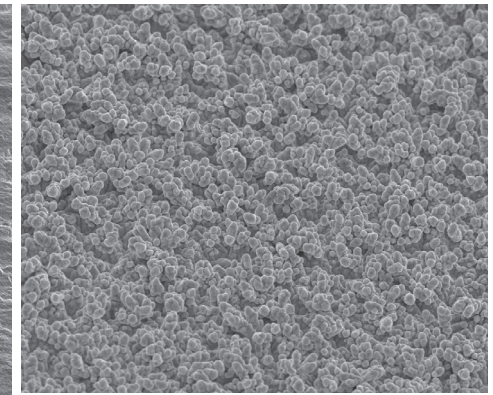
- PCB outer layers
- PCB inner layers

**Features:**

- IPC Grade III
- Treatment on matte side of foil
- High temperature lamination compatible



Untreated Drum Side  
H oz. /18 μm (1500x)



Treated Matte Side  
H oz. /18 μm (1500x)

**Typical Values:**

Attribute		Unit	Value					Reference
Thickness Designation			T	H	1	2	3	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		μm	12	18	35	70	103	
		oz.	3/8	1/2	1	2	3	
Area Weight		g/m <sup>2</sup>	106.8	152.5	305	610	915	
		g/254 in <sup>2</sup>	17.5	25	50	100	150	
		oz./ft <sup>2</sup>	0.375	0.5	1	2	3	
Roughness	Drum Side	μm	0.25					IPC-TM-650-2.2.17
		μ"	10					
	Matte Side	μm	5.1	6.4	10.2	15.4		
		μ"	200	250	400	606		
Tensile	Ambient	Kg/mm <sup>2</sup>	42	39	37	35	IPC-TM-650-2.4.18	
		Kpsi	60	55	53	49		
	180°C	Kg/mm <sup>2</sup>	21					
		Kpsi	30					
Elongation	Ambient	%	6	8	15	20	25	
	180°C	%	8	8	8	8	7	
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	0.89	0.98	1.16	1.25	1.50	IPC-TM-650-2.4.8
		Lbs/in	5.0	5.5	6.5	7	8.4	

\* Peel strength measured on 170°C Tg Epoxy

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